

ABSTRACT

Provided is a polishing pad comprising a fiber including organic fiber and a matrix resin holding the fiber, wherein at least the organic fiber is exposed on the work material-side surface thereof at least after dressing. The polishing pad suppresses generation of minute polishing scratches on the work material and allows flat polishing at low load. It is also possible to manage the polishing end point of the work material without generation of polishing scratch with its optical detection system monitoring the polishing state of work material. Thus, for example, it is possible to polish substrates under a small load on the interlayer insulating film and give products superior in flatness in semiconductor device manufacturing processes and thus, the polishing pad according to the invention may be used easily in the next-generation dual damascene method.